Stock code：603386

CHAMPION ASIA

致力于成为行业领先的
PCB/FPC制造及EMS配套服务提供商

PCB/FPC Manufacturing And SMT Services Provider

CHAMPION ASIA INTERNATIONAL ELECTRONIC LIMITED

GUANGDONG CHAMPION ASIA ELECTRONICS CO., LTD.

www.championasia.hk

Contents

People First ; Credit Based ;

Excellent Innovation ; Sustainable Operation ;

Company Profile

20

20 years
of development

1+6

1 Shenzhen Management Center
6 manufacturing base：
- Champion Asia:
Huizhou, Longnan, Vietnam;
- Multilayer: Changsha, Guangde, Zhuhai;

3

3 kinds of products:
PCB ;
FPC&RFPC ;
SMT ;

5

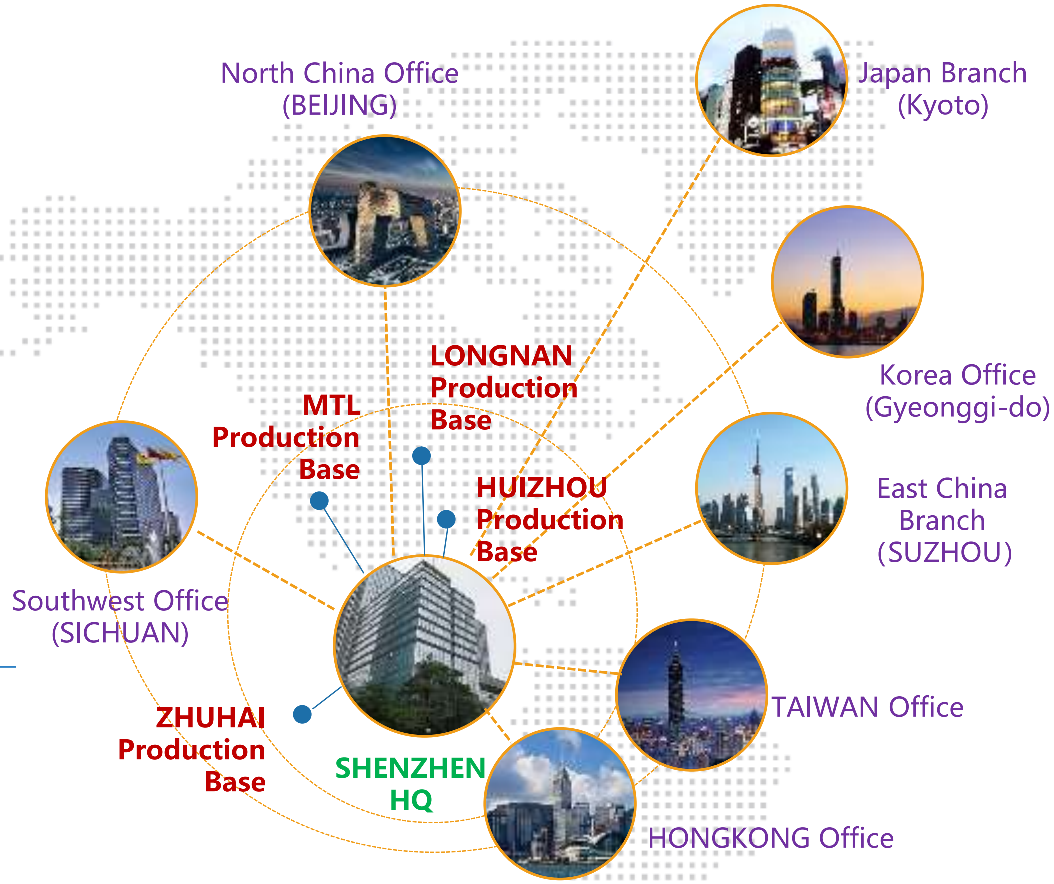
5 major manufacturing:
- MP of PCB;
- Medium batch of PCB;
- Small batch of PCB;
- R&D sample of PCB；
- SMT manufacturing;

8

8 factories:
- 3 PCB factories for MP;
- 3 PCB factories for sample and small batch;
- 1 FPC factory;
- 1 SMT factory;

100+

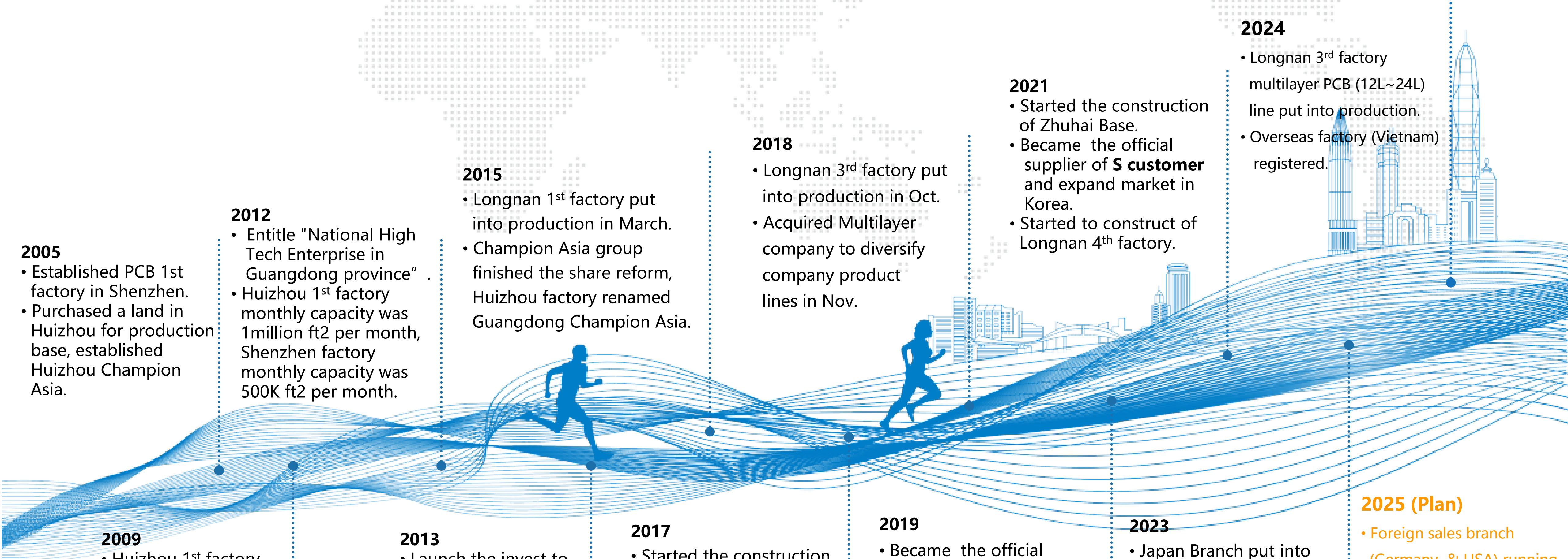
Provide excellent service to more than **100** customers all over the world



- Shanghai-listed company, stock code 603386 ,
- Perfect production and quality management system , and solid financial management system.
- Three major product lines: PCB, FPC&RFPC, PCBA,
- PCB Ranking: 56th all over the world, 36th overall in China, 21th domestic (CPCA 2024).

Development History

CHAMPION ASIA



2005
- Established PCB 1st factory in Shenzhen.
- Purchased a land in Huizhou for production base, established Huizhou Champion Asia.

2009
- Huizhou 1st factory put into production.
- Passed ISO9001, ISO14001,UL,CQC, TS16949 quality certification.

2012
- Entitle "National High Tech Enterprise in Guangdong province” .
- Huizhou 1st factory monthly capacity was 1million ft2 per month, Shenzhen factory monthly capacity was 500K ft2 per month.

2013
- Launch the invest to build new factory which cover about 400,000㎡ Jiangxi province Longnan county.

2015
- Longnan 1st factory put into production in March.
- Champion Asia group finished the share reform, Huizhou factory renamed Guangdong Champion Asia.

2017
- Started the construction of Longnan 3rd factory.
- Successfully listed on the Main -Board market of Shanghai Stock Exchange in Sep .

2018
- Longnan 3rd factory put into production in Oct.
- Acquired Multilayer company to diversify company product lines in Nov.

2019
- Became the official supplier of **H customer** and expand communication product market share.
- Launch the invest to build Zhuhai branch company.

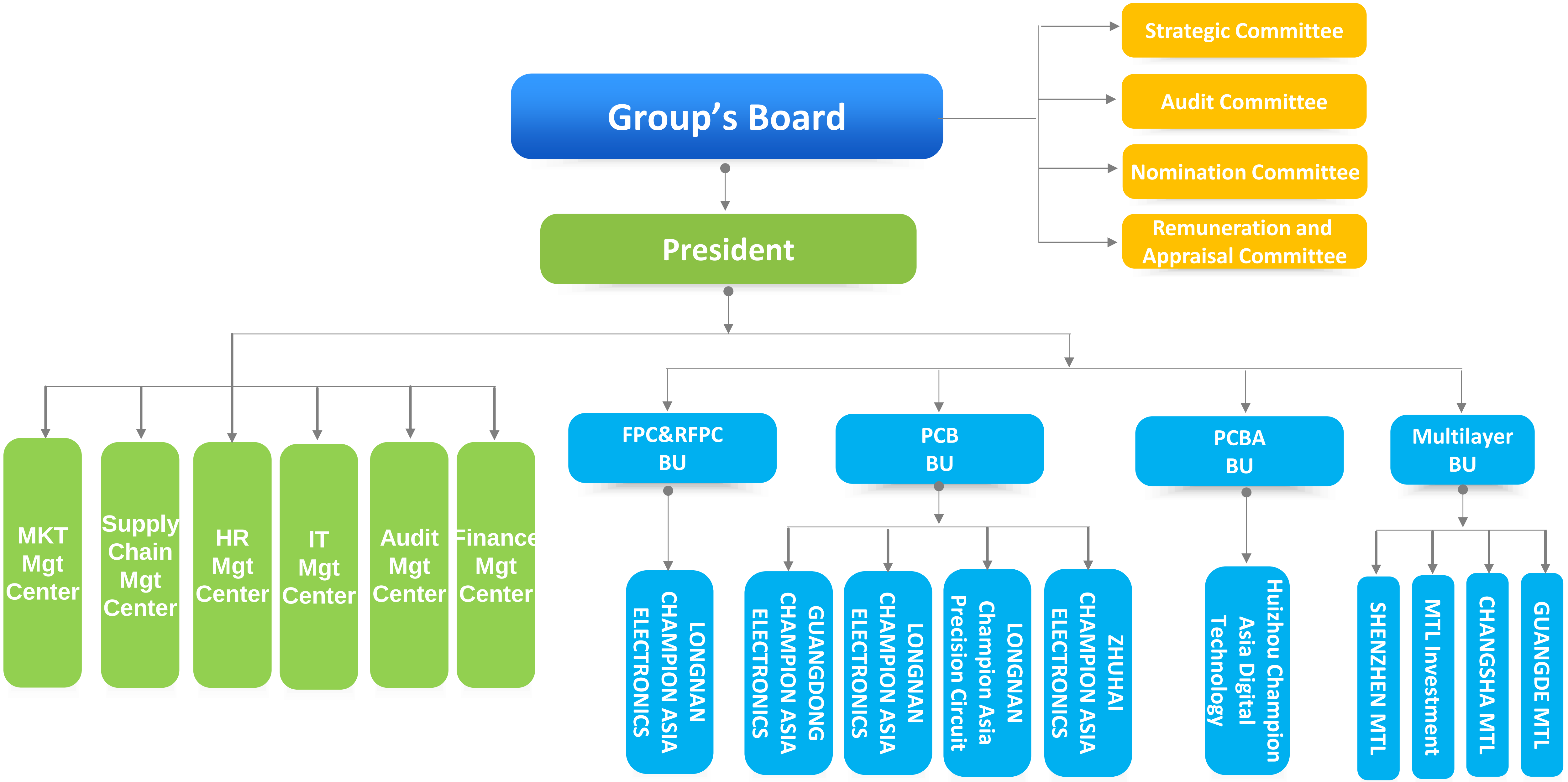
2021
- Started the construction of Zhuhai Base.
- Became the official supplier of **S customer** and expand market in Korea.
- Started to construct of Longnan 4th factory.

2023
- Japan Branch put into operation.
- Zhuhai factory(Phase 1) construction completed and put into production.

2024
- Longnan 3rd factory multilayer PCB (12L~24L) line put into production.
- Overseas factory (Vietnam) registered.

2025 (Plan)
- Foreign sales branch (Germany & USA) running.
- Longnan 3rd factory HDI PCB line put into production.
- Overseas factory (Vietnam) running in Q4.

Organizational Structure



Group's Board

Strategic Committee

Audit Committee

Nomination Committee

Remuneration and Appraisal Committee

President

MKT Mgt Center

Supply Chain Mgt Center

HR Mgt Center

IT Mgt Center

Audit Mgt Center

Finance Mgt Center

FPC&RFPC BU

- LONGNAN CHAMPION ASIA ELECTRONICS

PCB BU

- GUANGDONG CHAMPION ASIA ELECTRONICS
- LONGNAN CHAMPION ASIA ELECTRONICS
- LONGNAN Champion Asia Precision Circuit
- ZHUHAI CHAMPION ASIA ELECTRONICS

PCBA BU

- Huizhou Champion Asia Digital Technology

Multilayer BU

- SHENZHEN MTL
- MTL Investment
- CHANGSHA MTL
- GUANGDE MTL

Product Structure

6

Manufacturing bases

Huizhou: PCB (Medium & MP batch), SMT

Zhuhai: PCB (R&D sample, MP batch) , SMT

Changsha: Small batch of PCB

Guangde: R&D sample of PCB

Longnan: MP batch of PCB,FPC,RFPC

Vietnam (Build in progress): MP batch of PCB, SMT

Manufacturing base - Huizhou Base

Huizhou 1st factory（PCB factory)

- **Date of foundation**：2005 (produced at 2009)
- **Floor area**：50,000m2
- **Capacity**： 1,200,000 ft2/month
- **Product usage:** Focus on 4~12 layers PCB, mainly used inside Automotive Electronics, Industrial Control, Power, Energy, Communication, Security etc.

Manufacturing base - Longnan Base

Big Industrial Park with area of 400,000㎡;
Planning PCB/FPC/HDI/SMT production lines;
Huge production capacity with automated equipment and advanced production efficiency;

Longnan 1st factory (MP PCB factory)

- **Date of foundation:** 2013 (produced at 2015)
- **Floor area:** 178,000m2
- **Capacity:** 1,200,000 ft2/month
- **Product usage:** Focus on 4~12 layers PCB, mainly used Automotive, Security, Industrial Control, Mother board, Server, consumer Electronic etc.

Longnan 2nd factory (FPCB&RFPC factory)

- **Date of foundation:** 2016 (produced at 2016)
- **Floor area:** 27,000m2
- **Capacity:** 500,000 ft2/month
- **Product usage:** Focus on 2~10 layers FPC&RFPC, mainly used inside battery, TWS earphone, wireless charger, CCM, smart home application, etc.

Longnan 3rd factory (MP PCB factory)

- **Date of foundation:** 2016 (produced at 2018)
- **Floor area:** 70,000m2
- **Capacity:** 3,000,000 ft2/month
- **Product usage:** Focus on 2~24 layers PCB, mainly used Consumer Electronic, Industrial, Energy, Server, Automotive Communication, etc.

Longnan 4th factory (HDI PCB factory)

- **Date of foundation:** 2016 (plan to produce at 2024)
- **Floor area:** 60,000m2
- **Capacity:** 500,000 ft2/month
- **Product usage:** Focus on 4~8L HDI PCB, mainly used Consumer Electronic, Tablet PC, Industrial, Automotive Communication, etc.

Manufacturing base - Multilayer bases

Multilayer Zhuhai

Production capacity: 6000m² month
Production PNs: 12000 / month
Product features: ≤1m² samples and small batches for quick delivery.

Multilayer Changsha

Production capacity: 12000m²/month
Production PNs: 2700 / month
Product features: above 10m² batch service

Multilayer RFPC

Production capacity: 6000m²/month
Production PNs: 1000 / month
Product features: rigid -flexible combination, HDI, special board production

Guangde Multilayer

Production capacity: 6000 m²/month
Production PNs: 7800 / month
Product features: above 3m² medium and large batch service.

Manufacturing base - Zhuhai Base

Zhuhai factory focus on sample PCB,
High layers PCB, HDI, SMT manufacturing.

- Total floor area is 183479 m^2 , total covered area is 288980 m^2 , total green area is 33026 m^2 .
- Total capacity is 3,000,000 ft^2 /month, will be constructed in 3 phases.
- Phase I factory has been capped on 20th April 2022, Put into production on Oct 2023.

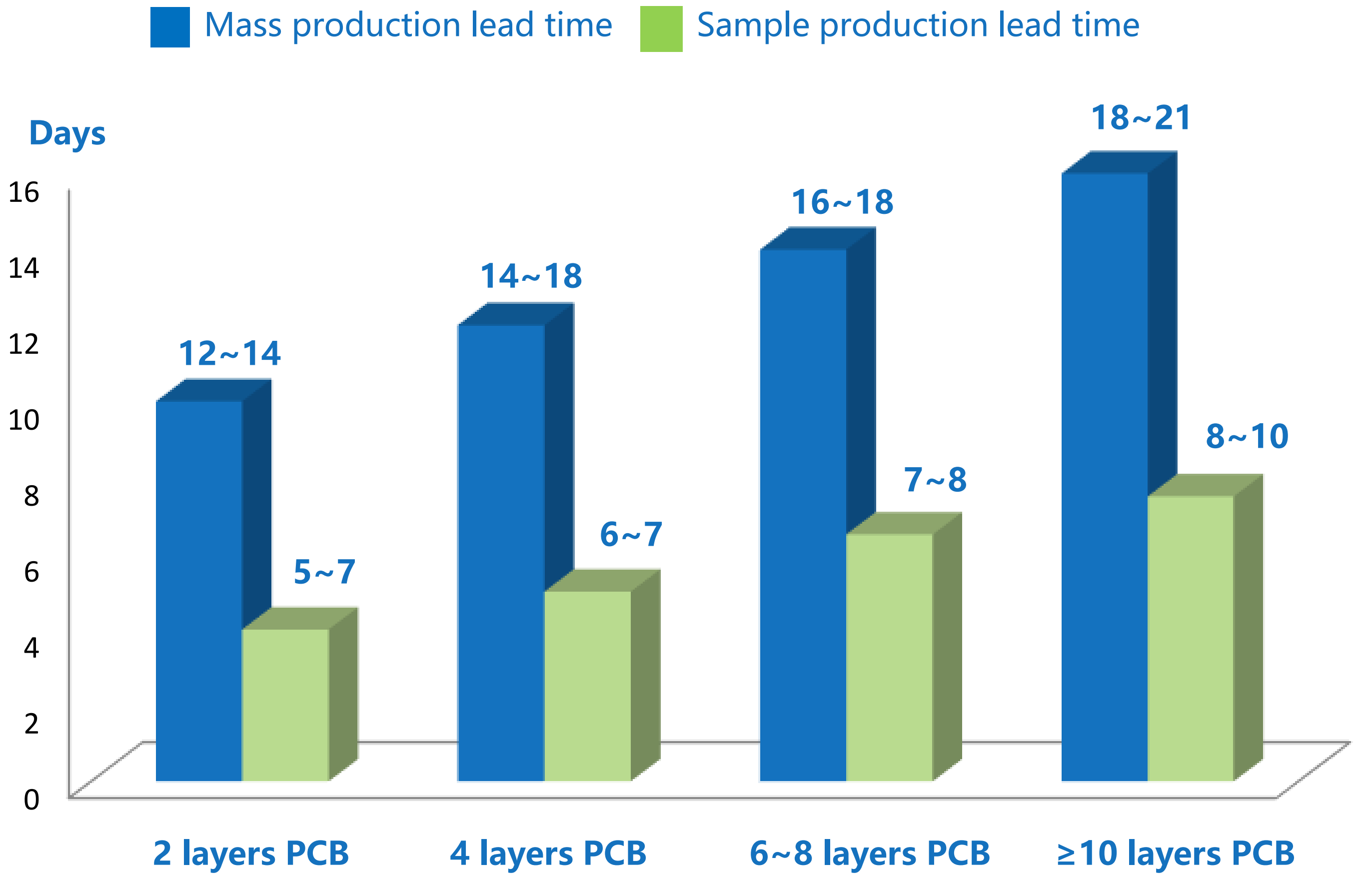
Manufacturing base - SMT bases

Huizhou 2nd factory （SMT factory)

- **Date of foundation：** 2009 (produced in 2010 and moved to new industrial park in 2021)
- **Floor area：** 24,000m2

Line	Unit	Qty	CAPA/M	Application
SMT	100M	28	20	Mother Board, TV Mainboard, STB, Consumer Electronic etc.
AI	Million	24	9.5	
DIP	10K	10	220	
SET	10K	10	235	

Product Lead time



Remark:

The above lead time is MP lead time standard, start after EQ confirm.

We can apply the special process to meet customer’ s urgent order.

★ Fast delivery capability:

Layers Count	Fastest delivery	Normal delivery
2L	24 hours	4 days
4L	48 hours	5 days
6L	60 hours	6 days
8L	72 hours	7 days
10L	96 hours	8 days
>10L	96 hours	8~12 days

Remark:

The above lead time belong to Multilayer BU,

Separate rates standard.

Product Application - MP batch of PCB

Consumer Electronics: 40%

TV	Refrigerator
STB	Washing machine
Speaks	Microwave oven
Router	Air conditioner

Energy: 25%

Solar inverter
Energy storage system
Converter
Charging pile
Network power

Computer and peripherals: 15%

Laptop
Desktop

Security & Industrial Control : 7%

Monitoring System	Industrial control
Intelligent building	Electric tool
Intelligent transportation	Robotic arms
The scanner	LED

Automotive: 8%

The dashboard
Intelligent Cabin
T-Box
Car antenna
Vehicle light control system

IT Communication: 5%

Server
Switches
Feature phones
The Bluetooth module

Product Application - Sample and Small batch of PCB

Industrial Controllers:

Mature mass production capability for rigid-flex board. Research and development of various special structural technologies. Adapting to the needs of intelligent products.

Security Products:

Stable and reliable quality. Manufacturing capability of special stack up. Process capability for special environmental requirements.

Automotive:

Strictly in accordance with IATF 16949 management system. Good quality control for high reliability boards. Satisfy the technological R&D needs of new energy vehicles.

Medical Products:

Long-standing recognition from multiple healthcare clients. Small footprint and fine PCBs for portable products.

Communications:

Manufacturing capability for high-layer PCB. Fabrication for big size and thick backplane PCB. Accurate impedance control. Various special materials support and mixed dielectric lamination. Special technology: Variable Length G/F, back drilling.

Power Supply:

UL listed thick copper board from 1oz to 6oz. Various types of high TG, high thermal conductivity materials. Manufacturing capability for copper busbar production. Fabrication of metal based(core), partially embedded copper coin board.

IOT Products:

Mature and reliable technologies like blind/buried vias, POFV and half hole plating. Fastest delivery time is 24 hours, which effectively assist clients in market development. Rich experience in various module production.

Military avionics:

Cutting-edge R&D capabilities. Capability of special products and special technologies available.

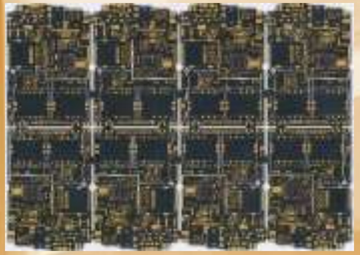
Product Classify - MP batch of PCB

Layers Count: 6L (OSP+ENIG)
Min drill hole diameter: 0.35mm
Line Width/Space: 3/3mil
Application: TV Mainboard

Layers Count: 6L (OSP)
Min drill hole diameter: 0.25mm
Line Width/Space: 3/3mil
Application: Motherboard

Layers Count: 4L (OSP)
Min drill hole diameter: 0.20mm
Line Width/Space: 3.9mil
Application: Consumer electronic

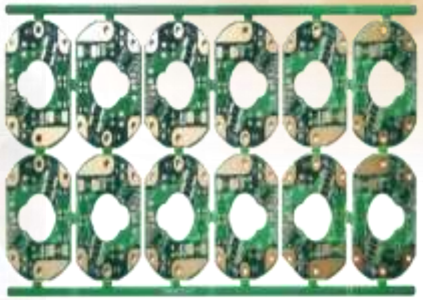
Layers Count: 6L (ENIG)
Min drill hole diameter: 0.25mm
Line Width/Space: 0.152/0.102mm
Application: Network Communication



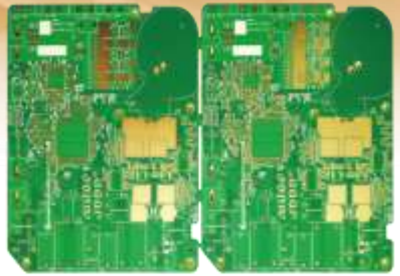
Layers Count: 4L(OSP+ENIG)
Min drill hole diameter: 0.25mm
Line Width/Space: 4/4mil
Application: Feature Phone

Layers Count: 10L (OSP)
Min drill hole diameter: 0.25mm
Line Width/Space: 3/3mil
Application: Server

Layers Count: 2L(ENIG)
Min drill hole diameter: 0.40mm
Line Width/Space: 4/4mil
Application: Automotive (Dashboard)



Layers Count: 4L(ENIG)
Min drill hole diameter: 0.30mm
Line Width/Space: 4/4mil
Application: Security



Layers Count: 4L(ENIG)
Min drill hole diameter: 0.30mm
Line Width/Space: 4/4mil
Application: Solar Inverter

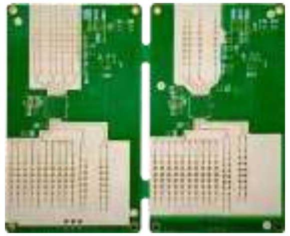
Layers Count: 4L(HASL LF)
Min drill hole diameter: 0.30mm
Line Width/Space: 5/5 mil
Application: LED Display

Product Classify - Sample and Small batch of PCB

High Frequency Board:

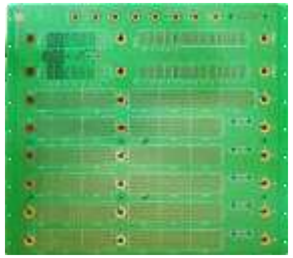
Max Layers: 24L
Material: Rogers, Taconic, Arlon, Panasonic, TUC, PTFE
Layer stack up: single material, mixed dielectric, metal base
Surface treatment: OSP, Immersion Gold, HASL,
Immersion Tin, Immersion Sliver

mm Wave Rader PCB:



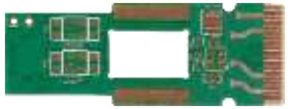
Material: PTFE+RF-4
Line width precision: ±8um
Special technology: Blind via, POFV
Advanced technology: Multilayer PCB with PTFE,
Hybrid pressing technology. E A: ≤15um

High Speed Backdrill PCB:



Material: Panasonic, TUC, Isola
Backdrill precision: ≤0.15um
Chosen technology: backdrill+ via filled by epoxy resin
Board thickness of backdrill PCB: ≤6.5mm

Optical transceiver:

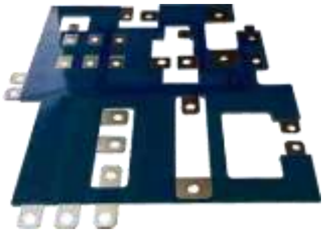


Material: FR-4, High frequency, High speed material
Gold finger size tolerance: ±0.075mm
Special technology: HDI (hole filling)
Signal transmission speed: ≤100Gbps

Copper Embedded PCB:

Structure: semi-embedded, fully embedded
Min embedded copper size: 3*3 mm
Min thickness of embedded copper: 0.5mm
Flatness of embedded copper to PCB ≤0.075mm

Busbar PCB:

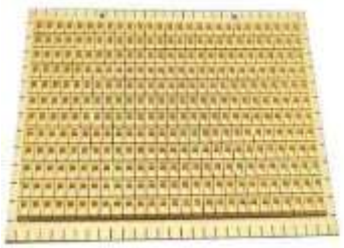


Busbar material: copper
Min conductor spacing: 0.8mm
Busbar copper thickness: 1.0~3.0mm
Finish board thickness: 2.0mm~10.0mm

Heavy copper PCB (Power supply):

Material: High TG, high thermal conductivity
Dielectric thickness ≥0.09mm
Inner copper weight: ≤12 OZ
Max layers: 24L
Feature technology: Thick copper PCB with stepped milling process

Ceramic substrate:



Special technology: DPC、DBC、COB
Min hole size: 0.10mm
Max copper thickness: 15um~200um
Surface treatment : Immersion Gold/Sliver
Board thickness: > 0.20mm
PTH: Via-filling plating, Vias filled with silver paste

Product Classify - Sample and Small batch of PCB

IC Test Board:

Max thickness: 6.0mm

Max aspect ratio: 25:1

Max gold thickness: 80u”

Bow and twist: ≤4‰

High Density multilayer PCB:

Min line width：3mil

Min drilling hole：0.2mm

Impedance control tolerance：±10%

Max layers count：108L

Step golden fingers PCB:

Layers count: ≤44L

Board thickness: ≥2.0mm

Gold finger thickness: ≤1.6mm±0.1mm

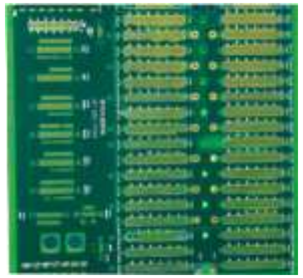
Gold finger slot precision：±0.05mm

Backplanes:

Max size: 1100mm*610mm

Max board thickness: 6.5mm

Max aspect ratio: 25:1



PCB with metal cores:

Metal material: Aluminum, Copper

Copper thickness: ≤12OZ

Layers count: single layer, double layer, multilayer metal cores

Thermal conductivity: 2-12w/m.k

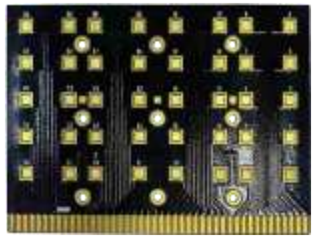
Thermoelectric separation PCB:

Material: Thermal conductivity of insulating layer (0.3-2w/m.k)

Thermal relief: Flat, sink

Outer layer copper foil (base): 0.5-18OZ

Copper base thickness: 0.8-3.2mm

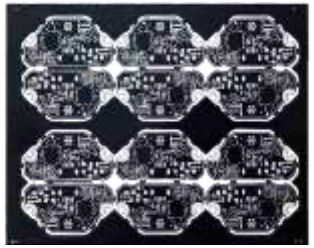


AIN embedded PCB:

Material: AIN

Ceramic coin size: 20*20mm

Professional technical support of complete thermal management.



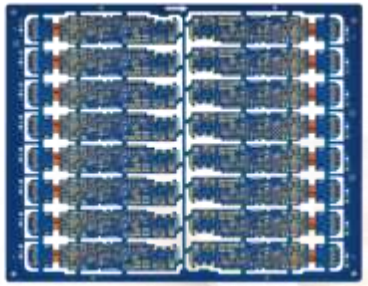
Rigid-flex PCB:

Max layers count: 16L

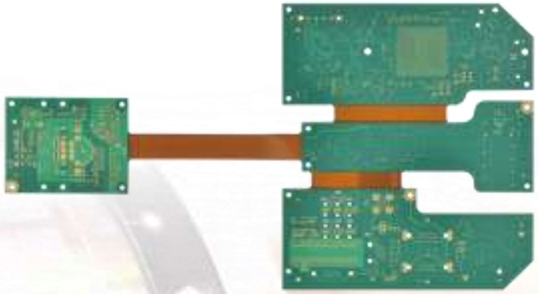
Max layers count for flex: 8L

Min line width: 2.5mil

Product Classify - FPC&RFPC



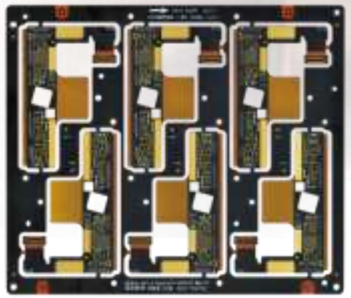
Layers Count: 6L RFPC
Min drill hole diameter: 0.10mm
Line Width/Space: 0.2 mm
Special Process: HDI / 2OZ Cu
Application: Electronic cigarettes



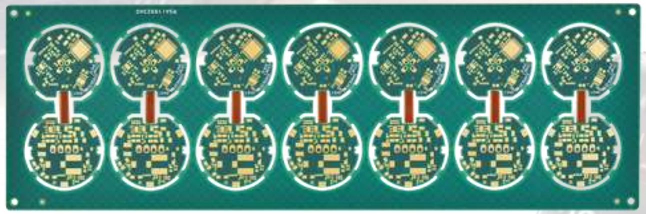
Layers Count: 10L RFPC
Min drill hole diameter: 0.20mm
Line Width/Space: 5/5mil
Special Process: Via in pad
Application: IT Communication

Layers Count: 8L RFPC
Min drill hole diameter: 0.10mm
Line Width/Space: 0.1mm
Special Process: HDI
Application: TWS Earphone

Layers Count: 4L FPC
Min drill hole diameter: 0.10mm
Line Width/Space: 3/4mil
Special Process: Stiffener
Application: Medical

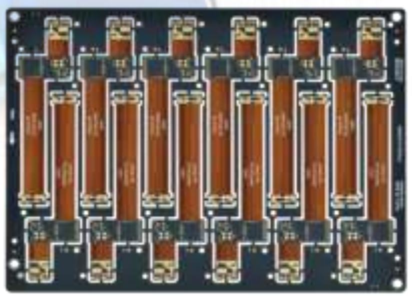


Layers Count: 6L RFPC
Min drill hole diameter: 0.10mm
Line Width/Space: 0.05mm
Special Process: HDI
Application: OLED



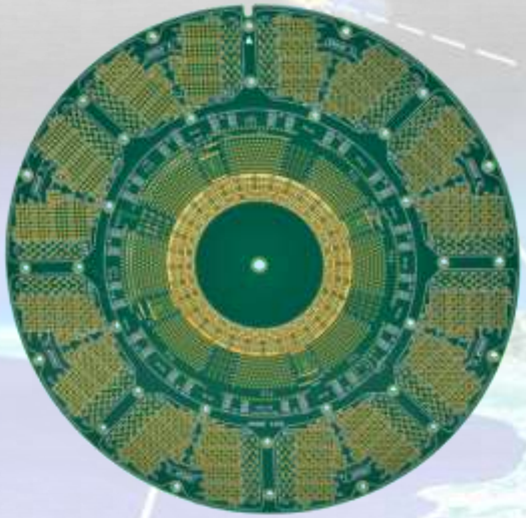
Layers Count: 10L RFPC
Min drill hole diameter: 0.2mm
Line Width/Space: 0.2mm
Special Process: HDI, resin plugging
Application: Industrial Control

Layers Count: 8L FPC
Min drill hole diameter: 0.1mm
Line Width/Space: 0.15mm
Special Process: HDI
Application: Mobile battery



Layers Count: 4L FPC
Min drill hole diameter: 0.15mm
Line Width/Space: 0.1mm
Special Process: ENEPIG
Application: CCM in Automotive

Product Classify – Special PCB



Layers Count: 30L

Min Drilling Hole Dia: 0.50mm

Line Width/Space: 5/5mil

Special Technology:

Countersink hole

Application: Semiconductor test

Layers Count: 108L

Board Thickness: 8.6mm

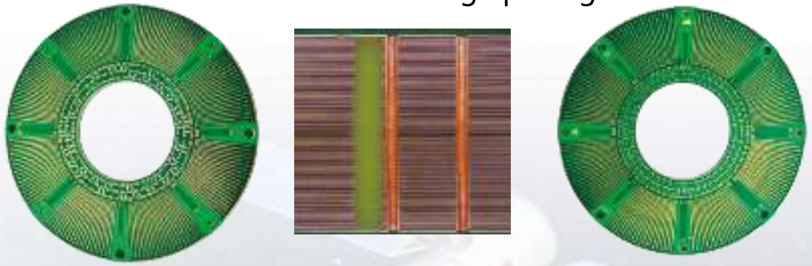
Min Drilling Hole: 0.50mm

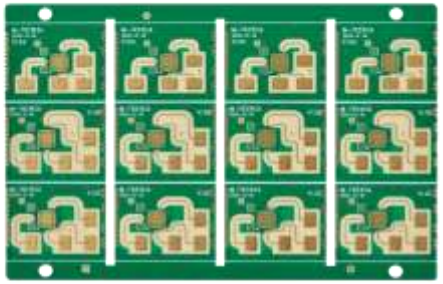
Aspect Ratio: 17.2 : 1

Hole to Line: 10mil

Special Technology:

Depth controlled hole,
edge plating



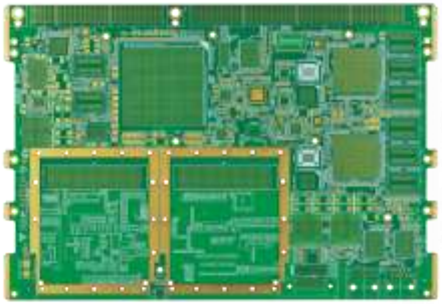


Layers Count: 10L

Min Drilling Hole Dia:
0.40mm

Line Width/Space:
0.203/0.24mm

Application: Aerospace



Layers Count: 20L

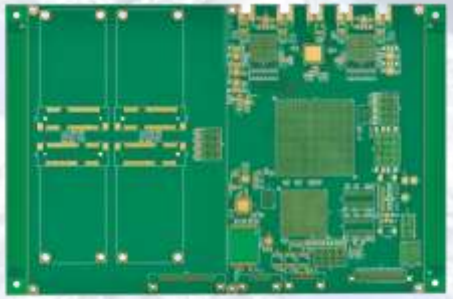
Min Drilling Hole Dia:
0.20mm

Line Width/Space: 3/3mil

Special Technology:

Backdrilling , Via in Pad

Application:
Communication



Layers Count: 16L

Min Drilling Hole Dia:
0.20mm

Line Width/Space: 4/4mil

Special Technology:

Backdrilling, Via in Pad

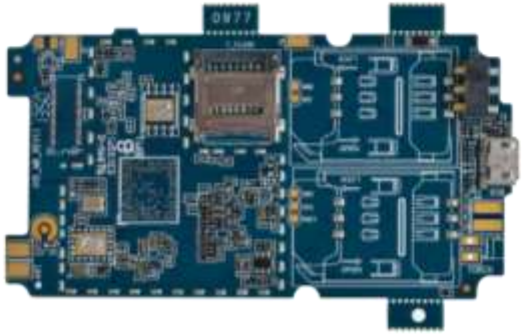
Application:
Communication

Product Classify - PCBA & OEM

TV PCBA

Automotive PCBA

Power Supply PCBA



Communication PCBA

Transparent LED Screen

Network Communication

Charging & Audio

Medical Product

Technology Capabilities - MP batch of PCB

Range	Item		Capabilities
Normal	Layers Count		≤24L
	Board Thickness		0.30-3.5mm
	Thickness Tolerance		±10%
	Max PNL Size		610mm*710mm
	Warpage(Min)		≤0.5%
	Impedance Tolerance	Differential impedance≥50Ω	±8%
		Characteristic impedance≤50Ω	±4 Ω
Stack up	PP Thickness		≥3.0mil
Drilling	Min Drilling diameter		0.15mm
	Hole diameter tolerance	PTH	±0.05mm
		NPTH	±0.025mm
Plating	Aspect Ratio of Plated Hole(Max)		20：1
Line Design	Inner Layer	Layers：4-10L	≥5 mil
		Layers: 12-16L	≥6 mil
	Inner Layer Line Width/Space	Inner Layer HOZ	2.5/2.5mil
	Max Base Copper	Inner Layer	≤5OZ
		Outer Layer	≤5OZ
	Outer Layer Line Width/Space		2.6/2.6mil
	Line width tolerance	Line width≥10mil	±2mil
		Line width＜10mil	±20%
	Pad Tolerance	Pad≥12mil	≥±10%

Range	Item		Capabilities
Solder Mask	Solder Mask Bridge		≥3mil
	S/M Plugging	Plugging hole diameter	0.25-0.60mm
	S/M Thickness	Line to surface	10-40um
		Line to corner	≥5um
Routing	Tolerance		±0.1mm
Surface Treatment	Gold-plated plug	Gold thickness	0.127-1.0um
		Ni thickness	2.54-8um
	ENIG	Gold thickness	0.03-0.10um
		Ni thickness	2.54-8.0um
	OSP	Film thickness	0.2-0.6um
	HASL lead free		1-25um
	Immersion Silver		6-15u"
	Immersion Tin		0.8-1.2um
Gold Finger	Gold thickness		0.127-0.8um
	Length Tolerance (Etching)		±0.15mm
	Length Tolerance (Solder Mask)		±5mil
	Width Tolerance		±2mil

Technology Capabilities - HDI PCB

Item		2025	2026	2027
Max Layers Count		12 L	18 L	24 L
HDI Blind Hole Strcture		3+N+3	5+N+5	7+N+7
Drilling hole diameter (um)	Min Blind Hole	75	75	75
	Min Buried Hole	150	150	150
	Min Through Hole	150	150	150
Max Aspect Ratio	Laser Blind Hole	0.8 : 1	0.9 : 1	1:01
	Through Hole	12 : 1	16 : 1	20 : 1
Min core without copper thickness (um)		50	50	50
Finish Board Thickness (mm)		0.80~2.4	0.30~2.8	0.25~3.2
Laser Hole Filling Dimple (um)		15	12	10
Hole Tolerance (um)	PTH	±50	±50	±40
	NPTH	±0.025	±0.025	±0.025
Warpage		≤0.6%	≤0.5%	≤0.4%
CNC Routing Tolerance (um)	Mass Production	±100	±75	±75
	Sample Production	±75	±50	±50
Impedance Tolerance		±10%	±8%	±8%
Line Capability (um)	Line Width	60~50	~45	~35
	Line Space	60~50	~45	~35
Min BGA Pad Size (um)		120~100	110~90	90~75
Min BGA Space (Pitch)		0.40mm	0.35mm	0.30mm

Technology Capabilities - Sample and Small batch of PCB

Range	Item		Sample batch Capa	Small batch Capa
Normal	Layers Count		≦108L	≦46L
	Board Thickness		0.2~13.0mm	0.4~6.5mm
	Thickness Tolerance		±8%	±10%
	Impedance Tolerance	Differential impedance≥50Ω	±8%	±10%
		Characteristic impedance≤50Ω	±2.5Ω	±5Ω
	Warpage(Min)		≦0.3%	≦0.75%
Stack up	PP Thickness		≧3mil	≧3mil
Drilling	Min Drilling diameter		0.125mm	0.15mm
	Hole diameter tolerance	PTH	±0.04mm	±0.05mm
		NPTH	±0.025mm	±0.05mm
Plating	Aspect Ratio of Plated Hole(Max)		25:1	12:1
Line Design	Inner Layer	Layers: 4-10L	≥5.5mil	≥6.5mil
		Layers: 12-16L	≥7mil	≥7mil
	Inner Layer Line Width/Space	Inner Layer HOZ	2.0mil/2.0mil	3mil/3mil
	Max Base Copper	Inner Layer	28OZ	6OZ
		Outer Layer	28OZ	6OZ
	Outer Layer Line Width/Space	30-40um	3/3mil	3/3mil
		40-55um	3.5/3.5mil	4/4mil
	Line width tolerance	Width≥10mil	±15μm	±1mil
		Width<10mil	±10%	±10%
	Pad Tolerance	Pad≥12mil	±1mil	±1mil

Range	Item		Sample batch Capa	Small batch Capa
Solder Mask	Solder Mask Bridge		3.5mil	4mil
	S/M Plugging	Plugging hole diameter	5mil	5mil
	S/M Thickness	Line to surface	10~40μm	10~40μm
		Line to corner	≧5μm	≧5μm
Routing	Tolerance		±0.1mm	±0.1mm
Surface Treatment	Gold-plated plug	Gold thickness	0.127~2μm	0.127~1.25μm
		Ni thickness	2.54~6μm	2.54~6μm
	ENIG	Gold thickness	0.03~0.2μm	0.03~0.2μm
		Ni thickness	2.54~6μm	2.54~6μm
	OSP	Film thickness	0.2~0.6μm	0.2~0.6μm
	HASL lead free		1~40μm	1~40μm
	Immersion Silver		6~15u"	6~15u"
	Immersion Tin		0.8~1.2μm	0.8~1.2μm
Gold Finger	Gold thickness		0.127-2μm	0.127-1.25μm
	Length Tolerance (Etching)		±0.15mm	±0.15mm
	Length Tolerance (Solder Mask)		±0.1mm	±0.1mm
	Width Tolerance		±25μm	±40μm

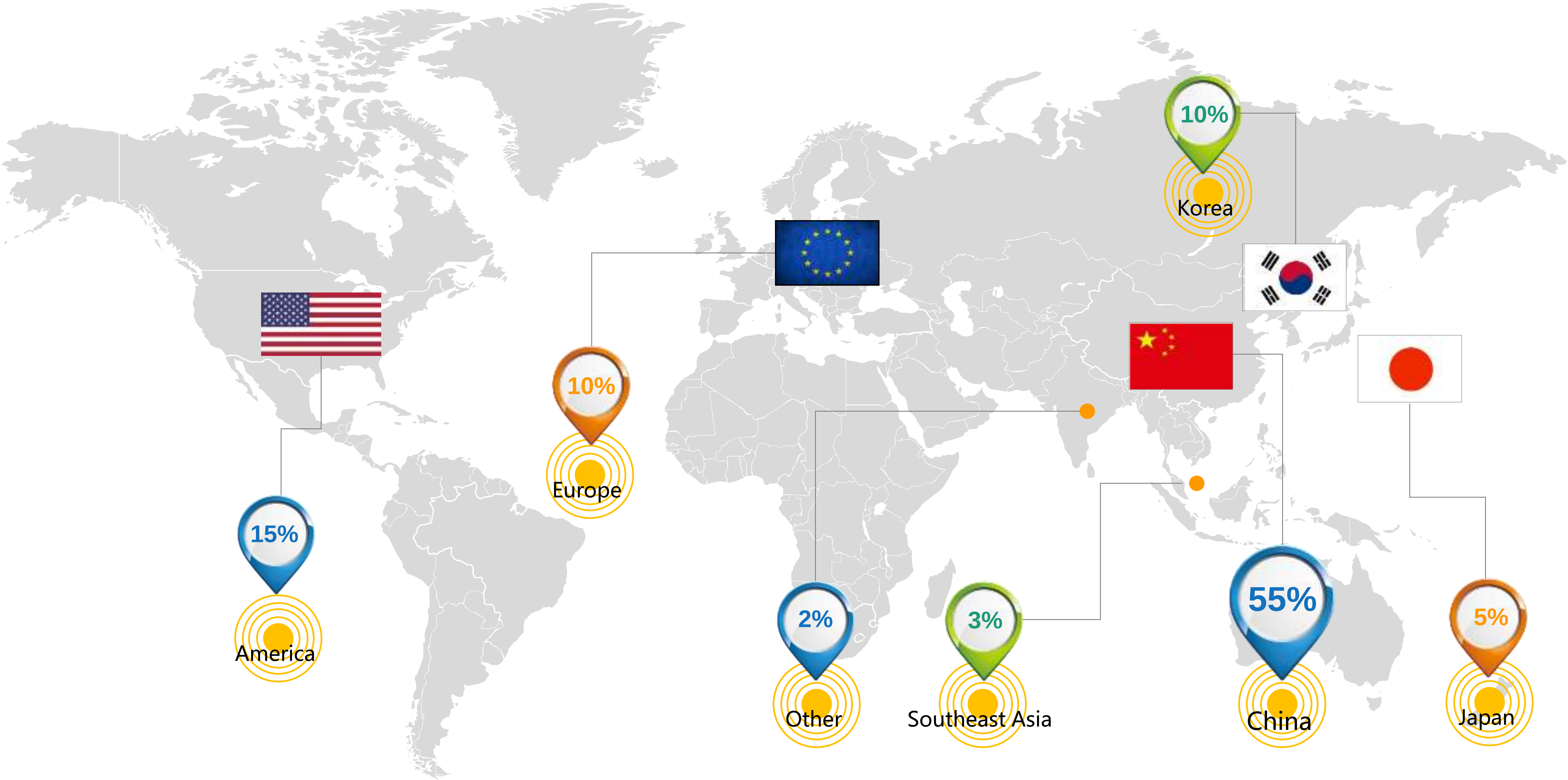
- **Surface treatment:** HASL lead free, immersion gold, immersion Tin, immersion Silver, Gold Finger, Hard/Soft gold plating, OSP, ENEPIG and Selective hard gold plating.
- **Materials:** FR4, Rogers, Arlon, Taconic, Bergguist, TUC, Panasonic M6/M7 and so on.
- **Special technology:** Blind & buried holes, Via in pad, Castellated holes, Counterbore, Step mounting holes, Controlled depth holes, edge-plating, metal base PCB, Stepped G/F, Back-drill, Mixed RF PCB, Busbar PCB, Copper coin embedded and Ceramic coin embedded.

Technology Capabilities - FPC & RFPC

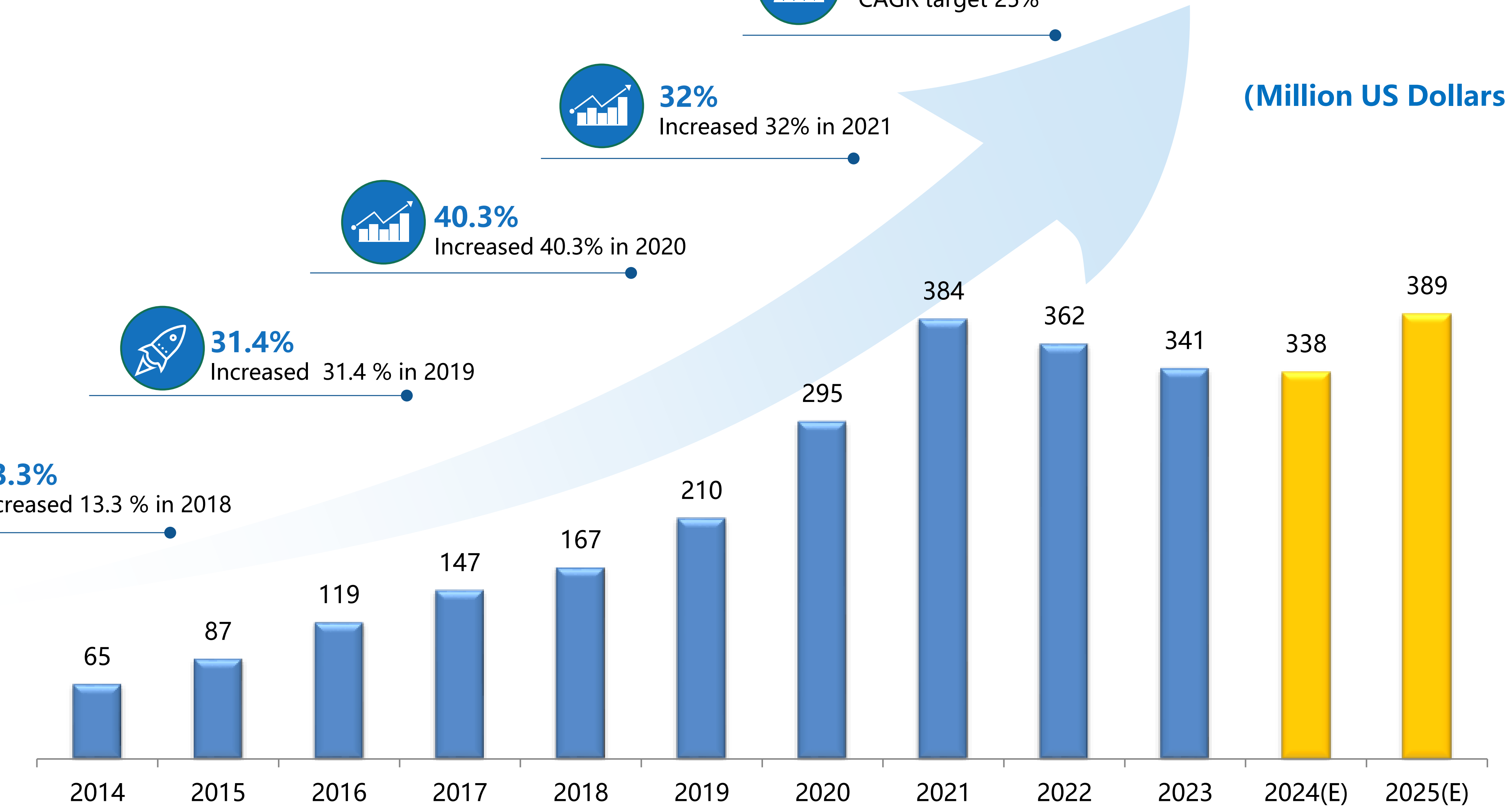
No.	Item	Capabilities
1	Layers Count	FPC：1-6L RFPC：2-10L
2	Finished Board Size(Max)	19.7″×19.7″
3	Major CCL Brand	Doosan\Thinflex\Shengyi\Taiyo\DongYi
4	Finished Board Thickness Tolerance	±0.03mm(Thickness≤ 0.2mm) ±0.05mm(0.2mm＜Thickness≤ 0.5mm)
5	Blind/Buried Hole	YES
6	Min Drilling Hole Diameter	Mech Drilling：0.1mm~6.5mm Laser Drilling：0.1-0.125mm
7	Base copper of outer layer	1/3 OZ-2OZ (0.012mm -0.070mm)
8	Base copper of inner layer	1/3 OZ-1OZ (0.012mm -0.035mm)
9	Board Thickness	0.07mm-2.0mm
10	Aspect Ratio of Plated Hole(Max)	8:1
11	Hole Diameter Tolerance (PTH)	±3mil (±0.075mm)
12	Hole Diameter Tolerance (NPTH)	±1mil (±0.025mm)
13	Copper Thickness of PTH Wall	10um min or base on customer requirement

No.	Item	Capabilities
14	Design Line Width /Space of inner layer (Min)	H/H OZ 3mil/3mil 1/1 OZ 4mil/4mil 2/2 OZ 5mil/5mil 3/3 OZ 6mil/6mil
15	Design Line Width /Space of outer layer (Min)	H/H OZ 3mil/3mil 1/1 OZ 3mil/3mil 2/2 OZ 4mil/4 mil 3/3 OZ 6mil/6mil
16	Solder Mask Bridge Width (Min)	2.5mil (0.064mm)
17	Solder Mask Alignment Tolerance	±2mil (±0.05mm)
18	Coverlay Bridge Width(Min)	8mil (0.2mm)
19	Coverlay Bridge Alignment Tolerance	±6mil (±0.15mm)
20	Dimension Tolerance (Hole to Edge)	±4mil (±0.1mm)
21	Test Capacity	PAD Size min　(0.1mm) PAD Pitch min (0.4mm)
22	Stiffener Type	PI\FR4\SUS
23	Electromagnetic Shielding Technology	Film / Silver Paste
24	Surface Treatment	OSP，ENIG，Plating Gold

Sale Areas


10%
Korea
10%
Europe
15%
America
2%
Other
3%
Southeast Asia
55%
China
5%
Japan

Sales Revenue



(Million US Dollars)

13.3%
Increased 13.3 % in 2018

31.4%
Increased 31.4 % in 2019

40.3%
Increased 40.3% in 2020

32%
Increased 32% in 2021

25%
CAGR target 25%

Serviced customers

Consumer Electronics:

SAMSUNG · Hisense · AOC · MI · CHANGHONG 长虹 · TCL · CVTE Dream·Future · Skyworth · SOLUM · Hansol

TV& Monitor& Projector · TV & STB · TV & Monitor · TV · TV & STB · TV & STB · TV&STB · TV · TV& Monitor& Projector

Solar & Stored Energy:

SUNGROW Clean power for all · HUAWEI · enphase ENERGY · flex · Salcomp · 锦浪科技 · ABB · FIMER

Solar & Stored Energy · Solar & Stored Energy · Solar & Stored Energy · Solar & Stored Energy · Solar Energy · Solar Energy · Solar Energy

Communication & Notebook:

ZTE · LITEON · hp · DELL · FOXCONN · STAR-NET 星网锐捷 · COMMSCOPE · H3C

IT Communication · Motherboard · Notebook · Notebook · Motherboard &Notebook · Network Communication · Network Communication · Server

Automotive:

BYD · 北斗星通 BDStar Navigation · HUAQIN · Visteon · Continental ContiTech · Kjima · 吉利汽车 GEELY AUTO · WULING · 上汽通用汽车 SAIC-GM · TOYOTA

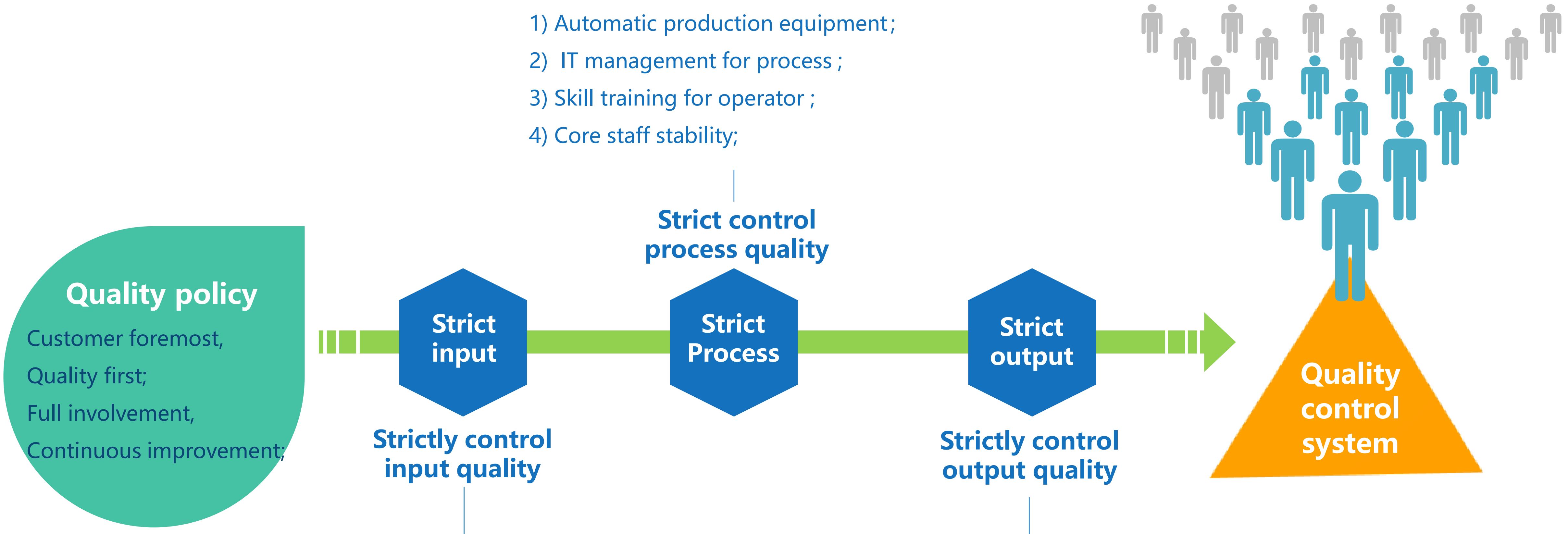
Tier1 & OEM · Tier 1 · Tier 1 · Tier 1 · Tier 1 · Tier 1 · OEM · OEM · OEM · OEM

Security & Industrial Control:

HIKVISION · alhua TECHNOLOGY · Honeywell · Schneider Electric · muRata INNOVATOR IN ELECTRONICS · Nidec · icape

Security · Security · Security · Industrial Control · Industrial Control · Industrial Control · Industrial Control

Quality Management



Quality policy

Customer foremost,

Quality first;

Full involvement,

Continuous improvement;

Strict input

Strictly control input quality

1) Key material purchased from brand manufacturer;
2) Non-key materials suppliers must be approved by quality dept;
3) Real-time monitor dynamic quality changes of suppliers;
4) Real-time update evaluation rating to ensure the good quality of suppliers;

Strict Process

Strict control process quality

1) Automatic production equipment;
2) IT management for process ;
3) Skill training for operator ;
4) Core staff stability;

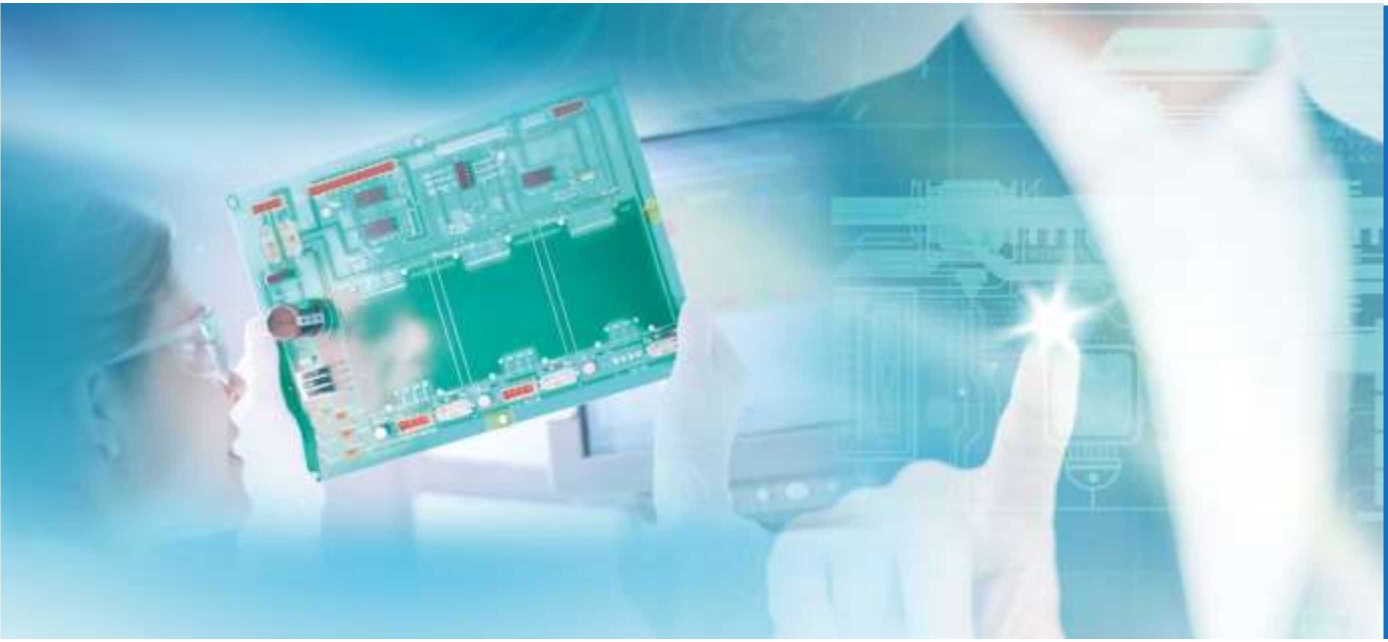
Strict output

Strictly control output quality

1) Benchmark customer quality standards;
2) Identify key quality control points ;
3) Establish a complete check list;
4) Lesson learn from each quality issue;

Quality control system

Product Certification



ISO9001：2015 management system certification

ISO14001：2015management system certification

IATF16949：2016 management system certification

OHSAS45001：2018management system certification

QC080000：2017management system certification

ISO27001：2013management system certification

ISO13485：2016 Medical management system

CQC Product Certification

UL Product Certification

RoHS environmental protection test

REACH environmental protection test

……

Major Equipment - PCB

Automatic Vacuum Lamination Machine

Automatic Return Line

Schmoll Drilling Machine

Major Equipment - PCB

Universal Horizontal PTH Line

Dongwei VCP Plating Line

Automatic Silk Screen Machine

LDI Exposing Machine

CNC Machine

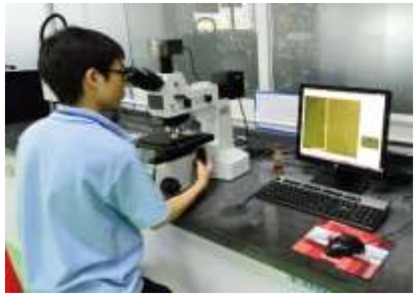
Automatic Electrical Test Machine

Major Equipment - PCB

Reliability Test Equipment (Partial)


RoHS Detector


Impedance Tester


Metallographic Microscope


Gold-nickel Thickness Tester


EDX Element Analysis


Reflow Oven

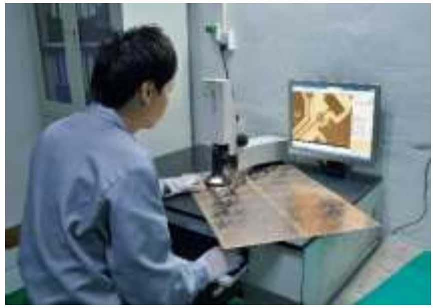

Soldering Pot


Thermal Shock Chamber


CTI Tester


Humidity Test Chamber


CAF Tester


Line-width/space Tester


IC Tester


Water Quality Detector


Layer Thickness Meter

Main equipment - FPC


Boffotto P26H-Plasma


Through-Hole Plating Line


Integrated U Type Vertical Continuous Plating Line


Double Track Vertical Continuous Plating Line


Jet Master Machine


Deburring & Desmear Machine


OSP Machine


XinHuaMei Immersion Gold Line

Major Equipment-SMT

SMT line

BGA welding X-ray detector

Odd shaped Components
Automatic Insert Machine

Warehouse

Fully Automatic Test Production Line

SMT Workshop

Main Advantage

Intelligentized ;
Networking ;
Digitization ;

Large-scale capacity ;
Modular production ;
Flexible capacity ;

MP of PCB ;
Medium batch of PCB ;
Small batch of PCB ;
R&D sample of PCB ;
SMT manufacturing ;

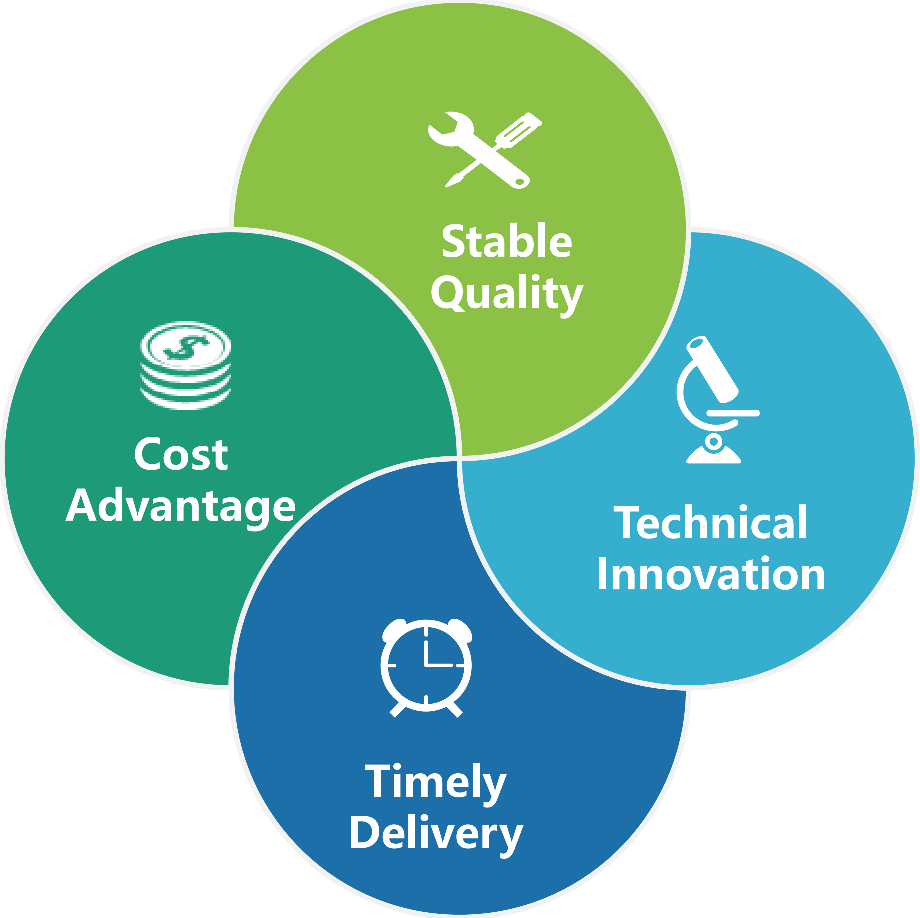
Intelligent Manufacturing

+

Huge and Flexible production capacity

+

Comprehensive product service



Stable Quality

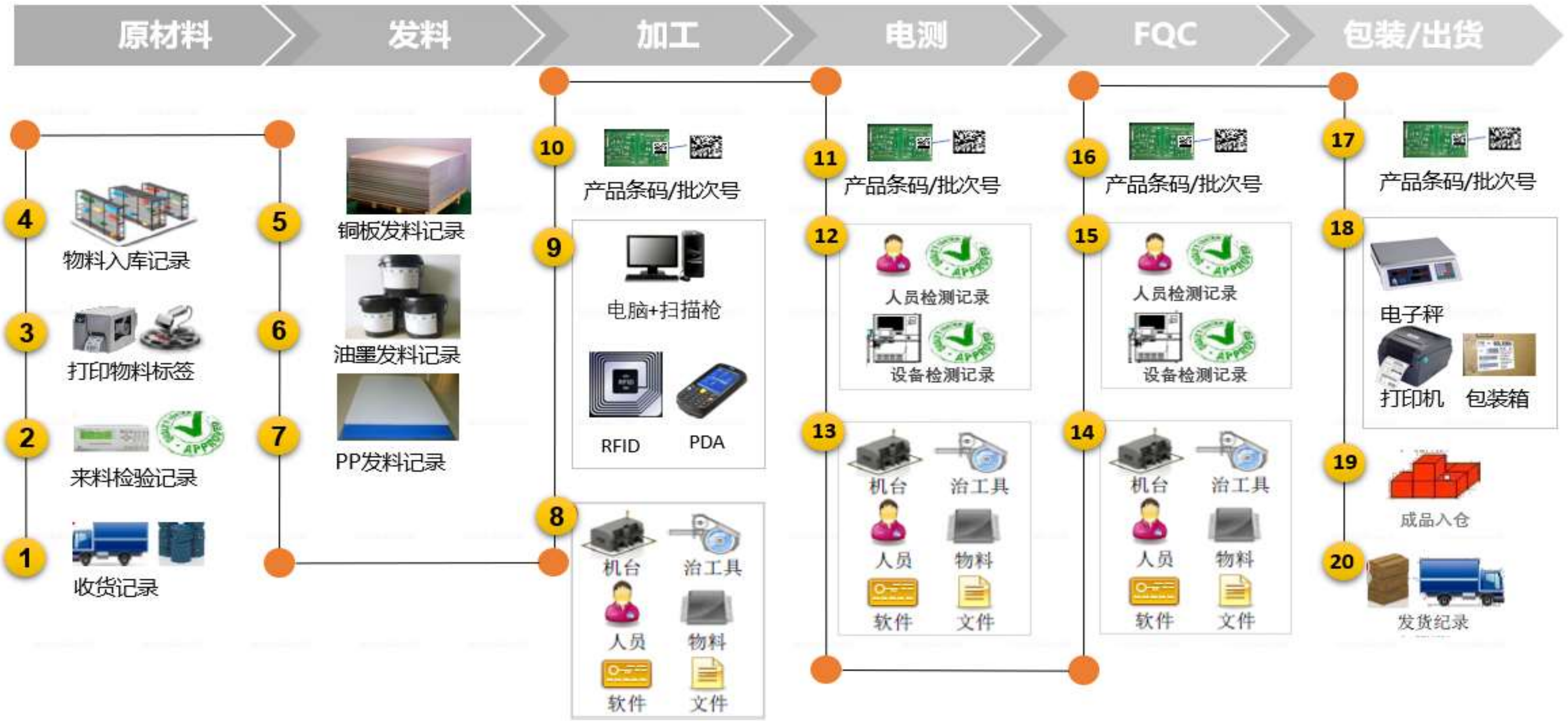
Cost Advantage

Technical Innovation

Timely Delivery

Intelligent Manufacturing - Fully process traceability

Raw Material → Warehouse → Production → Electrical Test → Final QC → Package / Outgoing



原材料 发料 加工 电测 FQC 包装/出货

1 收货记录

2 来料检验记录

3 打印物料标签

4 物料入库记录

5 铜板发料记录

6 油墨发料记录

7 PP发料记录

8 机台 治工具 人员 物料 软件 文件

9 电脑+扫描枪 RFID PDA

10 产品条码/批次号

11 产品条码/批次号

12 人员检测记录 设备检测记录

13 机台 治工具 人员 物料 软件 文件

14 机台 治工具 人员 物料 软件 文件

15 人员检测记录 设备检测记录

16 产品条码/批次号

17 产品条码/批次号

18 电子秤 打印机 包装箱

19 成品入仓

20 发货纪录

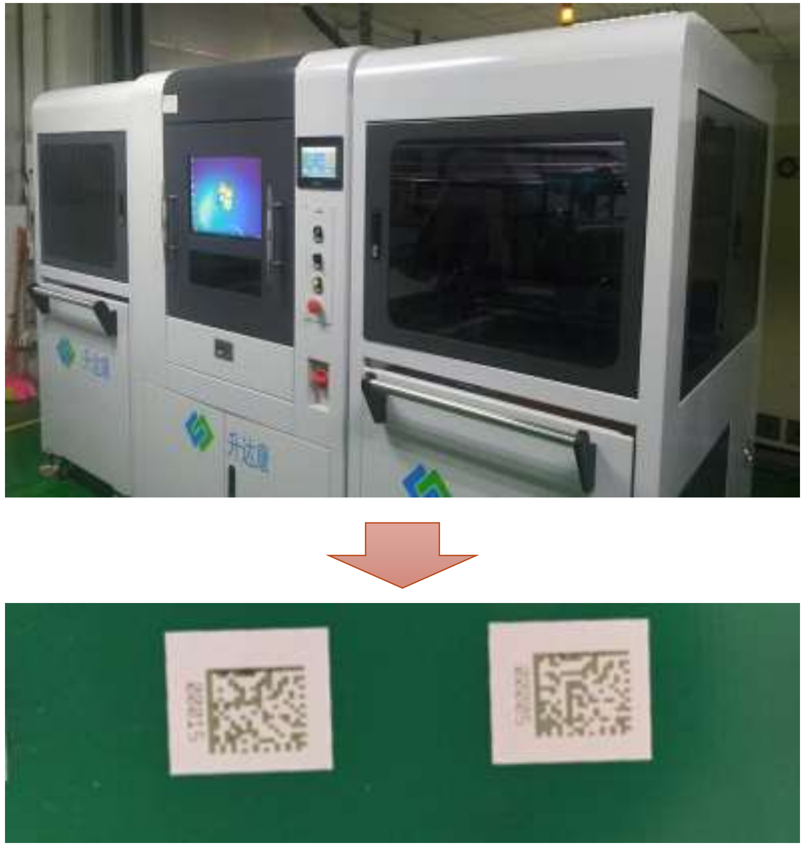
Intelligent Manufacturing - Product traceability

Inner Layer

Coding machine and PNL Code Printing

Outer Layer

Transcoding



Finishing PCB

Code Printing

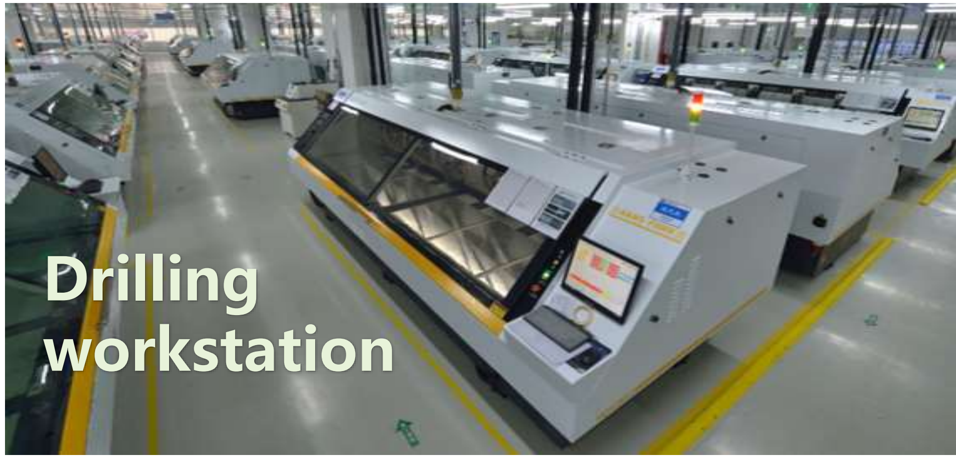
Intelligent Manufacturing - Exhibition of scene

Champion Asia applied intelligent management through automatic production machine/inspection machine/ERP system and China Unicom 5G bases, all kinds of data can be collected automatic and upload to cloud system for record and analysis.

LDI exposing workstation

Automatic film adhesive workstation

Scene of intelligent manufacturing



Drilling workstation

Plating / VCP workstation

Company glories

CHAMPION ASIA


国家企业技术中心
National Center for Enterprise Technology
国家发展改革委 科技部 财政部 海关总署 国家税务总局

National Enterprise Technology Center


专精特新 "小巨人"企业
龙南骏亚电子科技有限公司
工业和信息化部

Little Giant Enterprise


高新技术企业

National High-tech Enterprise


省级企业技术中心

Guangdong Enterprise Technology Center


广东省
车载智能终端线路板
工程技术研究中心
广东省科学技术厅
二〇一四年

Automotive PCB R&D Center


广东省知识产权示范企业

Intellectual Property Model Enterprise


CPCA

CPCA member of council


2019年企业上云典型案例
龙南骏亚"工业云平台"
工业和信息化部
二〇二〇年七月

Industrial Cloud Platform


江西省智能制造标杆企业

Benchmark enterprise of intelligent manufacturing


SKYWORTH 30
战略合作奖

SKYWORTH Strategic Cooperation Award

Excellent Supplier of **Mi**

Best Quality Award of **WH Foxconn**

Best Delivery Award of **TPV**

Excellent Supplier of **ChangHong**

Excellent Supplier of **BD Star**

Excellent Supplier of **Aihua**

Best Quality Award of **CVTE**

Excellent Supplier of **ADAYO**

Tech innovation Award from Shanghai Securities News


"5G+工业互联网"
应用示范企业
江西省工业和信息化厅
二〇二〇年五月

"5G+ Industrial Internet" Model Enterprises


2020年赣州市市长质量奖

The Mayor's Quality Award


龙头企业奖

Leading Enterprise Award


China unicom 中国联通
CHAMPION ASIA
PCB行业联合创新实验室

PCB Industry Joint Innovation Laboratory

- **National high-tech enterprise**
- **"A" taxpayer of Tax credit**
- **Guangdong Top 500 Manufacturing Enterprises**
- **Guangdong excellent brand model enterprises**
- **Guangdong excellent credit model enterprises**
- **Guangdong Innovation-oriented enterprises**
- **Provincial enterprise Technology Center of Guangdong**
- **Automotive PCB R&D Center in Guangdong**

- **National intellectual property advantage enterprises**
- **Guangdong intellectual Property Model enterprise**
- **Huizhou intellectual Property Model enterprise**
- **Productivity Promotion Award (Innovative Development)**
- **The Ministry of Industry and Information Technology "industrial cloud platform " model enterprise**
- **Department of Industry and Information Technology of Jiangxi Province "5G+ Industrial Internet" application model enterprises**
- **China Unicom PCB Industry Joint Innovation Laboratory**

Company Culture

Company Philosophy

People First ;

Credit Based ;

Excellent Innovation ;

Sustainable Management ;

Company Value

Take Social Responsibility ;

Cohesive of corporate culture ;

Practice people-oriented ;

Social Responsibility

Champion Asia comply with the laws and regulations strictly , implement green production and environmental protection activity.

Honest tax payment, targeted poverty alleviation, make contribution to the society.

ESG


龙南骏亚电子科技有限公司

2021年度江西省管理创新示范企业

江西省工业和信息化厅
二〇二二年三月

Leading enterprise for management innovation


龙南县"百企帮百村"精准扶贫行动

先进单位

Leading enterprise for poverty alleviation


发展升级示范企业

二〇一九年二月

Leading enterprise for development

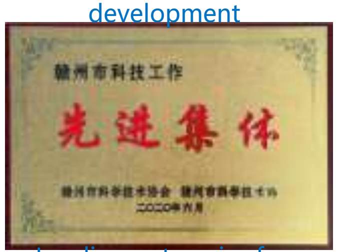

龙南民族团结

先进单位

Leading enterprise for national unity


先进基层党组织

Leading enterprise for primary party


赣州市科技工作

先进集体

2020年6月

Leading enterprise for Scientific and technical


共筑中国梦 守护童安行
系列安全图书捐赠活动

爱心单位

Caring enterprise for Book donation


爱心企业

Caring enterprise for fight floods


工人先锋号

江西省总工会

Worker Pioneer


先进非公有制企业

Leading enterprise for non-public ownership


2016年度工会工作

先进单位

Leading enterprise for labor union


授予：广东骏亚电子科技股份有限公司

防控新冠肺炎疫情
爱心捐赠单位

Donation enterprise for COVID-19 prevention


Excellent environmental protection facilities


荣誉证书

广东骏亚电子科技股份有限公司：

经评委会审定，贵企业被授予 2017 年度"广东省优秀信用示范企业"称号。

特颁此证。

Excellent credit model enterprise


江西省工业和信息化厅

Green Factory


纳税信用 A 级荣誉证书

A taxpayer of tax payment credit

Social Responsibility

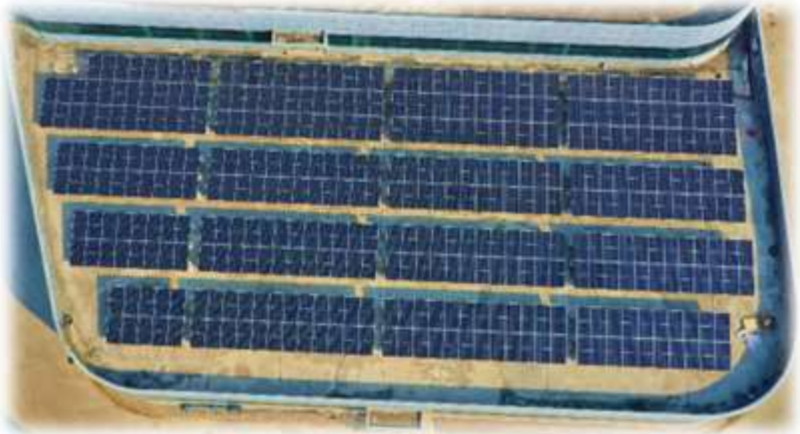
Champion Asia implemented the national dual carbon policy, each plant is equipped with rooftop photovoltaic power stations.
The use of clean electricity significantly reduces carbon dioxide and sulfur dioxide emissions from the factory.

Huizhou PCB Plant:

A total of 400KW photovoltaic power stations have been installed, providing 410,000 KWH of clean electricity for the factory every year, annual emissions of 410 tons of carbon dioxide and 12 tons of sulfur dioxide can be reduced.

Huizhou SMT Plant:

A total of 1600KW photovoltaic power stations have been installed, providing 1,640,000 KWH of clean electricity for the factory every year, annual emissions of 1642 tons of carbon dioxide and 50 tons of sulfur dioxide can be reduced.



Longnan Industrial Park:

A total of 1600KW photovoltaic power stations have been installed, providing 2,100,000 KWH of clean electricity for the factory every year, annual emissions of 2155 tons of carbon dioxide and 64 tons of sulfur dioxide can be reduced.

Location

Sketch Map Between each factory in China

Convenient transportation and logistics, less than 300 kilometers from Guangdong to Longnan.

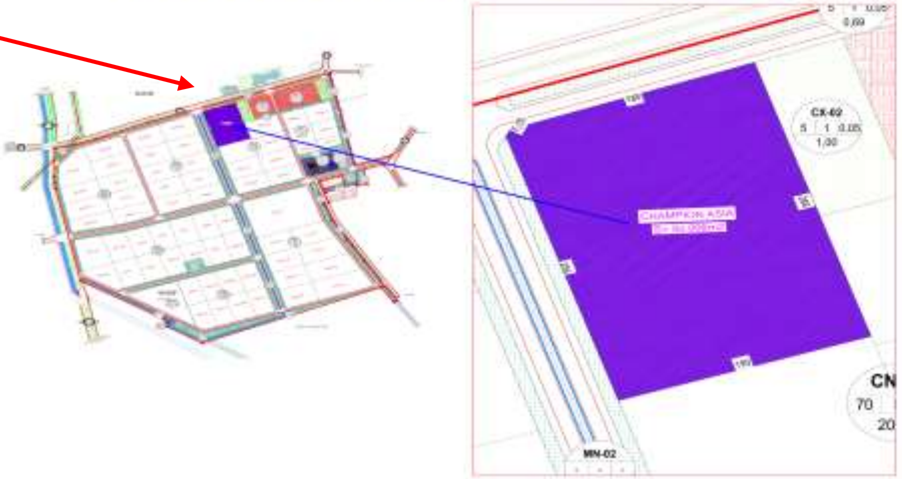
The whole journey from Shenzhen to Longnan just need 1.5 hours by high speed train or 3~4 hours by car.

PS: Status of our oversea factory

- **Country:** Vietnam;
- **Location:** Le Ho Province,
  Kim Bang 1# Industrial Park;
- **Logistic:** 87km far away Hanoi airport.
  140km far away Haiphong harbor.
- **Floor Area:** 50,098 ㎡

- **Construction:** Start from Mar 2025;
- **Production:** Plan to trial run at Mar 2026;
- **Capacity:** 200,000 ㎡ per month, mainly on 2~12L PCB and SMT;

CHAMPION ASIA - 50.098m2



PS: Status of our oversea factory

Le Ho Province
Kim Bang 1# Industrial Park

Champion Asia
Vietnam Plant

PS: Status of our oversea factory

DỰ ÁN: XÂY NHA MAY JUNYA (VIỆT NAM)
工程名称: 建造 骏亚科技（越南）公司厂

CHỦ ĐẦU TƯ: CÔNG TY TNHH CÔNG NGHỆ JUNYA VIỆT NAM
业主：骏亚科技（越南）公司
THIẾT KẾ : CÔNG TY CỔ PHẦN XÂY LẮP HOÀNG NGUYÊN
设计单位：黄源建设股份公司

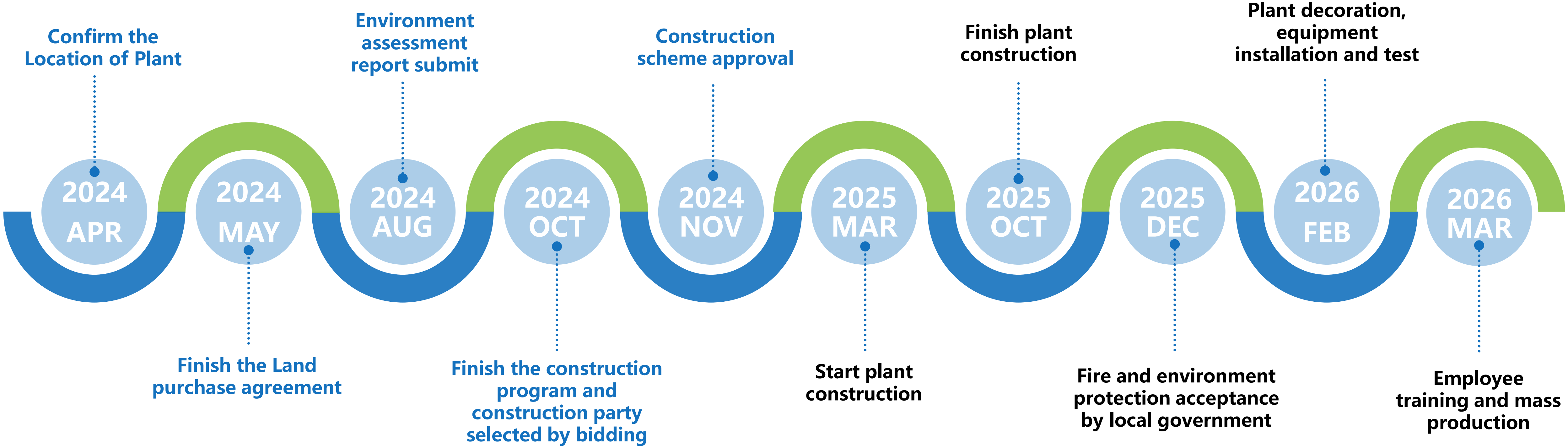
CHỦ ĐẦU TƯ/ 业主
CÔNG TY TNHH CÔNG NGHỆ JUNYA VIỆT NAM
骏亚科技（越南）公司

THIẾT KẾ/ 设计单位
CÔNG TY CỔ PHẦN XÂY LẮP HOÀNG NGUYÊN
黄源建设股份公司

HANOI - 2024

PS: Status of our oversea factory

Time Schedule of Vietnam Plant



Thank You

Champion Asia Group
CHAMPION ASIA INTERNATIONAL ELECTRONIC LIMITED

Guangdong Champion Asia Electronics Co., Ltd.
Huizhou Champion Asia Precision Circuit Co., Ltd.
25 Digital Industrial Park, Sandong Town, Huicheng District , Huizhou City,
Guangdong Province ,China .
Huizhou Champion Asia Digital Technology Co., Ltd.
(Plant 1),No.103 Jinfu Road, Xiaojinkou Subdistrict, Huicheng District, Huizhou
City Guangdong Province ,China .

Longnan Champion Asia Electronics Technology Co., Ltd.
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